

SID

Factory: Rot am See

Article:

520

ML6

Provided:

Kracht, Enrico

Customer:

Date:

10.08.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	<div><div>1</div><div>2</div><div>3</div><div>4</div><div>5</div><div>6</div><div>7</div><div>8</div><div>9</div><div>10</div><div>11</div><div>12</div><div>13</div></div> <div>A01</div> <div>B00</div> <div>A02</div>

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1921 µm

Version 1.2.14.15

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